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some other techniques, the chip 22 is coupled to the conductive traces. As aforesaid, the conductive traces are on the substrate for providing electrical connective paths. One end of the bonding wire is connected to the chip 22 via a conductive pad formed thereon, the other end of the bonding wire 26 is connected to a solder ball of a BGA array 28 formed on the lower-sided surface (second major surface) of the substrate 20 via the conductive traces.

IN THE CLAIMS:

Please cancel Claims 1 through 6, 10, and 13 through 26 without prejudice and without dedication or abandonment of the subject matter thereof.

Please amend Claims 7 and 12 and add new Claims 27 through 32 as follows:

7. (Amended) A semiconductor package, comprising:

a substrate;

a die located and supported on said substrate with an adhesive layer between them;

a plurality of signal transferring means which electrically connects said die to said substrate;

a molding compound which seals and protect said die and said plurality of signal transferring means, wherein said molding compound has geometrically a concave at the top surface of the center part ; and

a heat-spreading device which is attached atop said molding compound to conduct heat from said die to ambient air, wherein said head spreading device

DI
2

has a downward bump aligned to said concave; and

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a plurality of conductive means attached below said substrate to electrically connect a plurality of conductive traces on said substrate to external circuits.

D3
12. (Amended) The semiconductor package of claim 7, wherein said die has a thermally conductive glue, which conduct heat from said die through said molding compound to said heat-spreading device.

D4
27. (New) A semiconductor package, at least comprising:
molding means, with a concave located at the central part of the top surface, for sealing and protecting a die, which is adhered on a substrate by an adhesive layer and electrically connected to the substrate by a plurality of signal transferring means; and
heat-spreading means for conducting heat from said die to ambient air by attaching atop said molding means, wherein said head spreading means has a downward bump aligned to said concave.

28. (New) The semiconductor package of claim 27 further comprises a plurality of conductive means attached below said substrate to electrically connect a plurality of conductive traces on said substrate to external circuits.

29. (New) The semiconductor package of claim 28, wherein said plurality of conductive means includes a plurality of solder balls.